











-High heat resistance & removable-

Protection film/back tape "PF series"

Example of use

 Protection films/back tapes are used in various applications in a wide range of fields.

as temporary protection for circuits of substrate (Plating, etching & others)

as a temporary reinforcement for film or thin product

as a molding tape for QFN

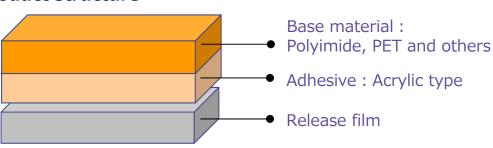
as a temporary fixing for small parts (embedded component substrate)

etc....

Characteristics

- High heat resistance and good chemical resistance. Durable to reflow or plating process.
- Silicone free tape, no concern from deterioration of chemical solution and silicone contamination of adherend.
- Wide range of tackiness lineups. (tackless, low, and high tackiness)

Product structure



■ Appearance



Product lineup

Tackless type PFE

Easy handling for cut and use in small size processing.

Low tackiness **PFG**

(Ex.) for temporary fixing of parts

High tackiness **PFR**

Enable to laminate at room temperature

Tackiness Lov

(Requires pressing for lamination)

High



Sales & Marketing Department

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